

600V, 30A, Trench FS II Fast IGBT

General Description:

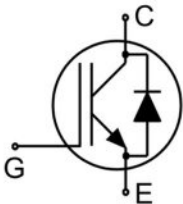
Using MJ's proprietary trench design and advanced FS (Field Stop) second generation technology, the 600V Trench FSII IGBT offers superior conduction and switching performances, and easy parallel operation;

Features

- ◆ Trench FSII Technology offering
- ◆ Very low $V_{CE(sat)}$
- ◆ High speed switching
- ◆ Positive temperature coefficient in $V_{CE(sat)}$
- ◆ Very tight parameter distribution
- ◆ High ruggedness, temperature stable behavior

Application

- ◆ Air Condition
- ◆ Inverters
- ◆ Motor drives



Schematic diagram



TO-247

Package Marking and Ordering Information

Device	Device Package	Device Marking
MJ30TD60BT	TO-247	MJ30TD60BT

Absolute Maximum Ratings ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Units
Collector-Emitter Voltage	V_{CES}	600	V
Gate- Emitter Voltage	V_{GES}	± 30	V
Collector Current	I_C	60	A
Collector Current @ $T_c = 100^{\circ}\text{C}$	I_C	30	A
Pulsed Collector Current, t_p limited by T_{jmax}	I_{Cplus}	90	A
turn off safe operating area, $V_{CE}=600\text{V}$, $T_j=150^{\circ}\text{C}$	-	90	A
Diode Continuous Forward Current @ $T_c = 100^{\circ}\text{C}$	I_F	30	A
Diode Maximum Forward Current	I_{FM}	90	A
Power Dissipation @ $T_c = 25^{\circ}\text{C}$	P_D	190	W
Power Dissipation @ $T_c = 100^{\circ}\text{C}$	P_D	95	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +175	$^{\circ}\text{C}$
Maximum Temperature for Soldering	T_L	260	$^{\circ}\text{C}$
Short circuit withstand time $V_{GE}=15.0\text{V}$, $V_{CC}\leq 400\text{V}$, Allowed number of short circuits<1000Time between short circuits: $\geq 1.0\text{s}$, $T_j\leq 150^{\circ}\text{C}$	t_{sc}	5	us

Thermal Characteristic

Parameter	Symbol	Value	Units
Thermal Resistance, Junction to case for IGBT	$R_{\theta JC}$	0.78	°C/W
Thermal Resistance, Junction to case for Diode	$R_{\theta JC}$	1.08	°C/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	40	°C/W

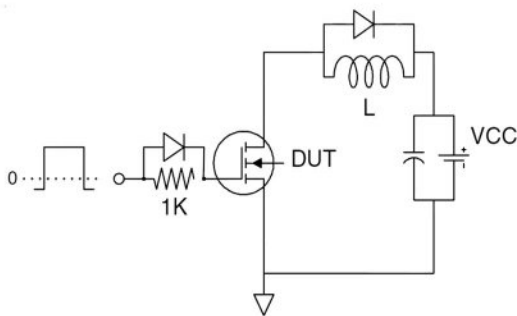
Electrical Characteristics (T_c=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Value			Units
				Min	Typ	Max	
Static Characteristics							
Collector-Emitter Breakdown Voltage	V _{(BR)CES}	V _{GE} =0V,I _{CE} =1mA		600	-	-	V
Collector-Emitter Leakage Current	I _{CES}	V _{GE} =0V,V _{CE} =600V		-	-	4	uA
Gate to Emitter Forward Leakage	I _{GES(F)}	V _{GE} =+30V,V _{CE} =0V		-	-	200	nA
Gate to Source Reverse Leakage	I _{GES(R)}	V _{GE} =-30V,V _{CE} =0V		-	-	200	nA
Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _C =30A V _{GE} =15V	T _J =25°C	-	1.7	1.9	V
			T _J =150°C	-	1.9	-	V
Gate Threshold Voltage	V _{GE(th)}	I _C =1mA, V _{CE} =V _{GE}		4.0	5.0	6.0	V
Dynamic Characteristics							
Input Capacitance	C _{ies}	V _{CE} =25V,V _{GE} =0V, f=1MHz		-	3552	-	pF
Output Capacitance	C _{oss}			-	106	-	pF
Reverse Transfer Capacitance	C _{rss}			-	67	-	pF
Gate Charge	Q _{Gate}	V _{CC} =480V, I _C =30A V _{GE} =15V		-	132	-	nC
Gate to Emitter Charge	Q _{ge}			-	28	-	nC
Gate to Collector Charge	Q _{gc}			-	54	-	nC
Short circuit collector current Max.1000 short circuits Time between short circuits: ≥1.0s	I _{C(SC)}	V _{GE} =15V,V _{CC} ≤400V, t _{sc} ≤5us,T _J ≤150°C		-	190	-	A
Switching Characteristics							
Turn-on Delay Time	t _{d(ON)}	V _{CC} =400V,I _C =30A V _{GE} =0/15V, R _g =5Ω Inductive Load		-	19	-	ns
Rise Time	t _r			-	17	-	ns
Turn-Off Delay Time	t _{d(OFF)}			-	166	-	ns
Fall Time	t _f			-	16	-	ns
Turn-On Switching Loss	E _{on}			-	0.36	-	mJ
Turn-Off Switching Loss	E _{off}			-	0.32	-	mJ
Total Switching Loss	E _{is}			-	0.68	-	mJ

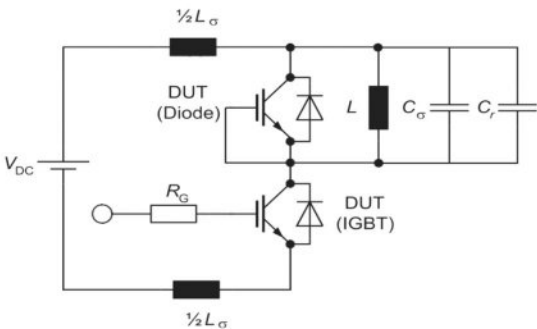
Electrical Characteristics of the Diode (Tc= 25°C unless otherwise specified):

Parameter	Symbol	Test Conditions	Rating			Units
			Min	Typ	Max	
Diode Forward Voltage	V _{FM}	I _F =30A	-	1.7	1.9	V
Reverse Recovery Time	T _{rr}	I _F =30A, di/dt=200A/uS	-	178	-	ns
Diode Peak Reverse Recovery Current	I _{RRM}		-	4	-	A
Reverse Recovery Charge	Q _{rr}		-	0.4	-	uC
Pulse width ttp≤380μs,δ≤2%						

Test Circuit

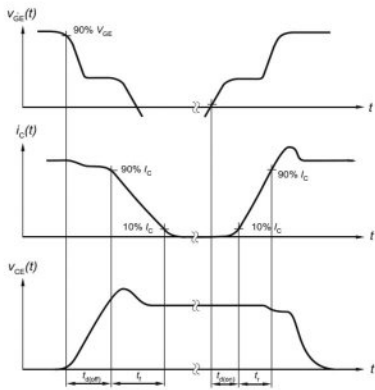


Gate Charge Test Circuit

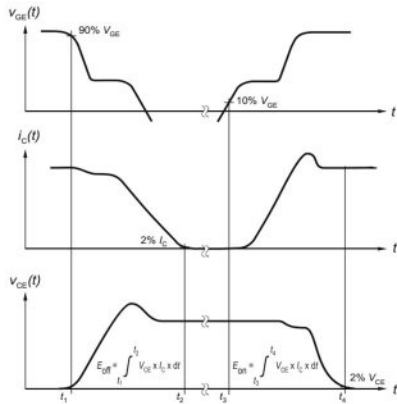


Switch Time Test Circuit

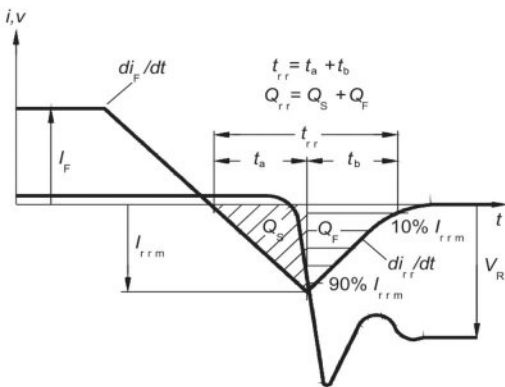
Switching characteristics



definition of switching times

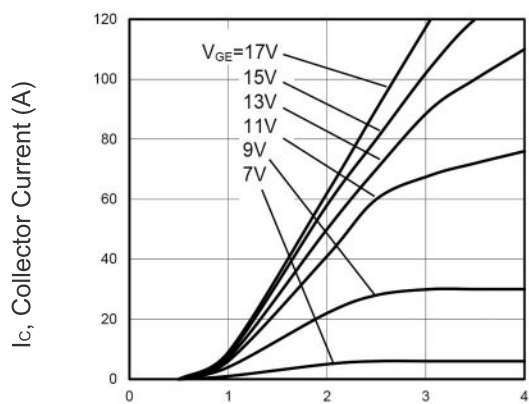


definition of switching losses



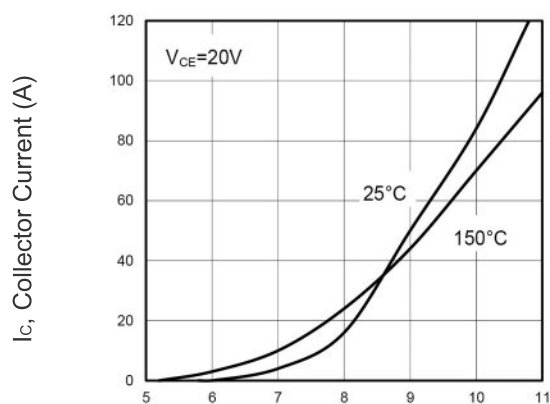
Definition of diode switching characteristics

Typical Electrical and Thermal Characteristics



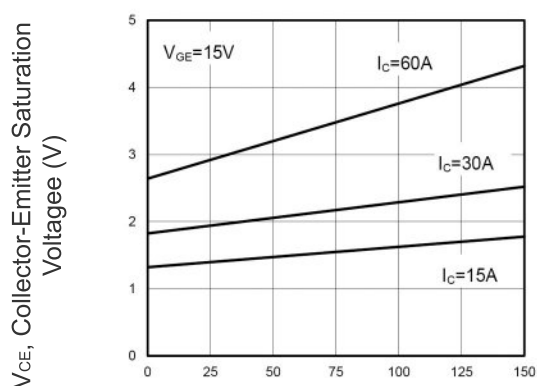
V_{CE} , Collector-Emitter Voltage (V)

Figure 1 Output Characteristics



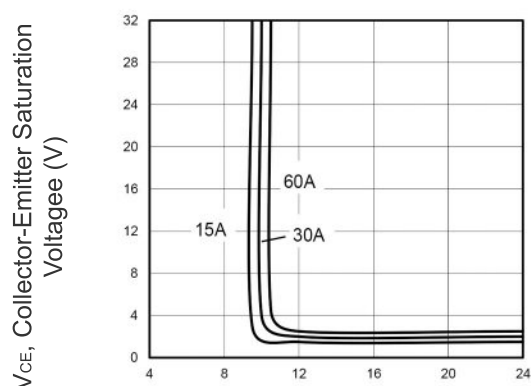
V_{GE} , Gate-Emitter Voltage (V)

Figure 2 Transfer Characteristics



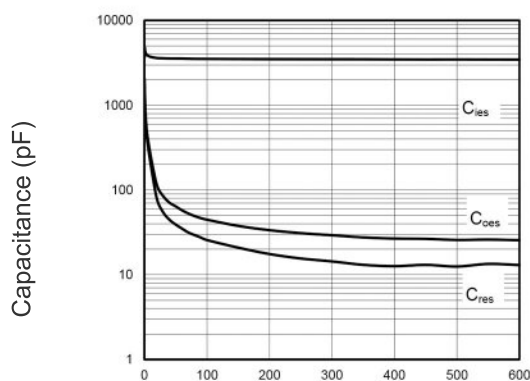
T_J , Junction Temperature ($^{\circ}C$)

Figure 3 V_{CEsat} vs. Case Temperature



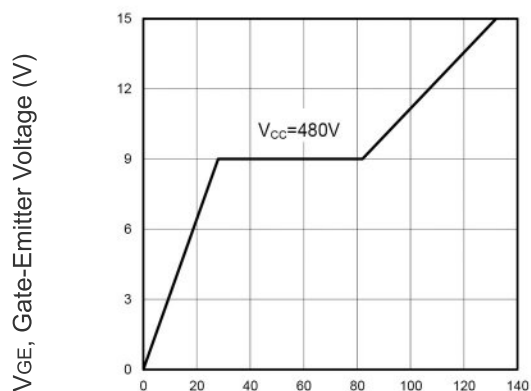
V_{GE} , Gate-Emitter Voltage (V)

Figure 4 Saturation Voltage vs. V_{GE}



V_{CE} , Collector-Emitter Voltage (V)

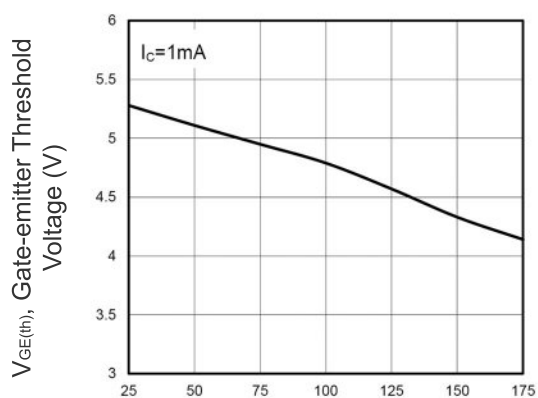
Figure 5 Capacitance Characteristics



Q_G , Total Gate Charge (nC)

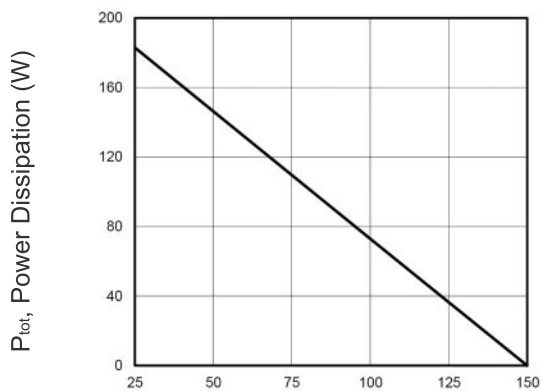
Figure 6 Gate charge waveform

Typical Electrical and Thermal Characteristics



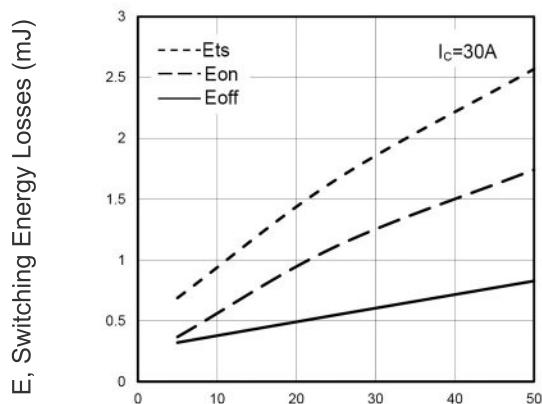
T_J, Junction Temperature (°C)

Figure 7 Gate-emitter Threshold Voltage as a Function of Junction Temperature



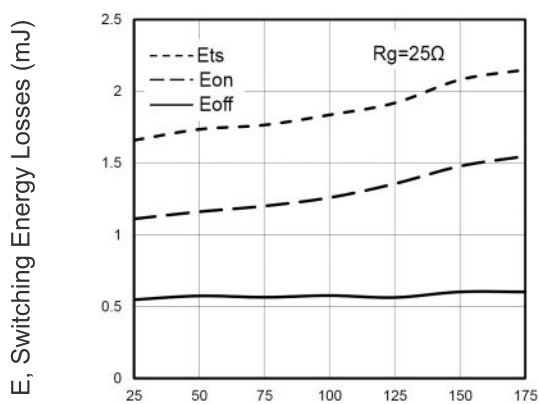
T_C, Case Temperature (°C)

Figure 8 Power Dissipation as a Function of Case Temperature



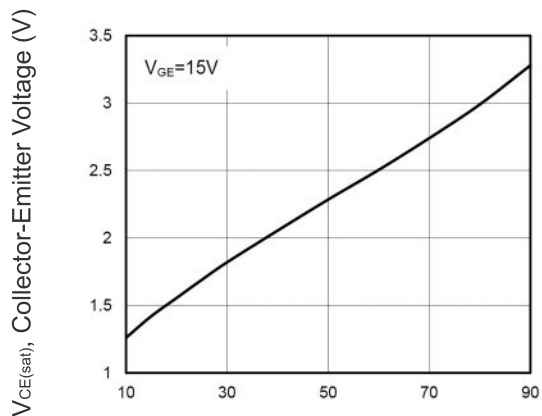
R_G, Gate Resistor (Ω)

Figure 9 Typical Switching Times as a Function of Gate Resistor



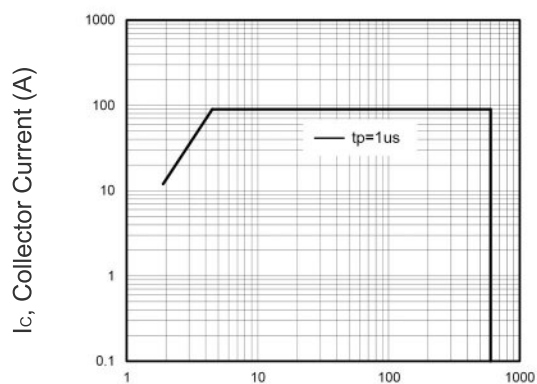
T_J, Junction Temperature (°C)

Figure 10 Typical Switching Times as a Function of Junction Temperature



I_C, Collector Current (A)

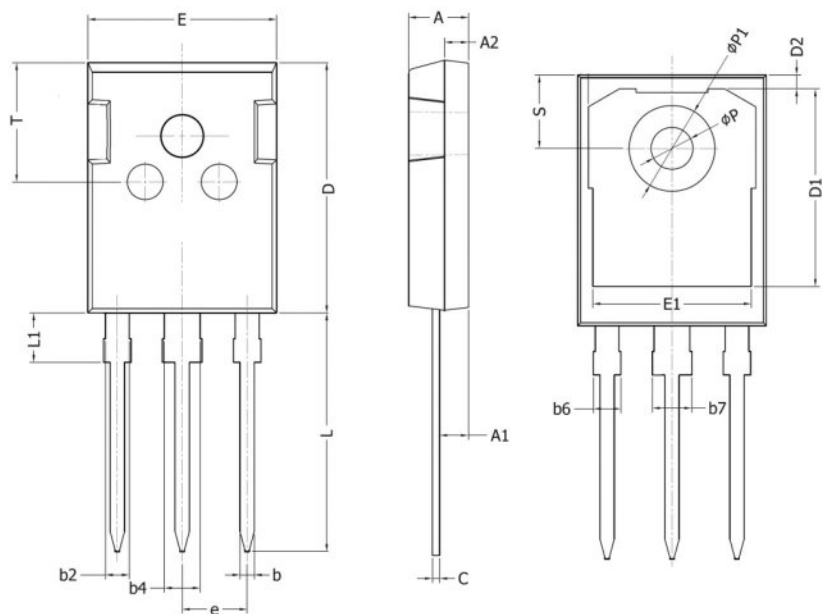
Figure 11 Typical Collector-emitter Saturation Voltage as a function of Collector Current



V_{CE}, Collector-Emmitter Voltage (V)

Figure 12 Forward Bias Safe Operating Area

TO-247-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.90	5.10	0.193	0.201
A1	2.31	2.51	0.091	0.099
A2	1.9	2.1	0.075	0.083
b	1.16	1.26	0.046	0.050
b2	1.96	2.06	0.077	0.081
b4	2.96	3.06	0.117	0.120
b6	-	2.25	-	0.089
b7	-	3.25	-	0.128
C	0.59	0.66	0.023	0.026
D	20.90	21.10	0.823	0.831
D1	16.25	16.85	0.640	0.663
D2	1.05	1.35	0.041	0.053
E	15.70	15.90	0.618	0.626
E1	13.10	13.50	0.516	0.531
e	5.436 BSC		0.214 BSC	
L	19.80	20.10	0.780	0.791
L1	-	4.30	-	0.169
P	3.40	3.60	0.134	0.142
P1	7.00	7.40	0.276	0.291
S	6.05	6.25	0.238	0.246
T	9.80	10.20	0.386	0.402

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